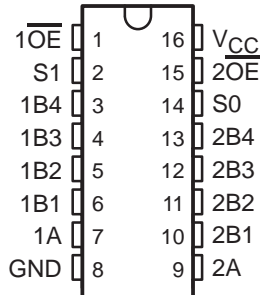


# SN74CBT3253 DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

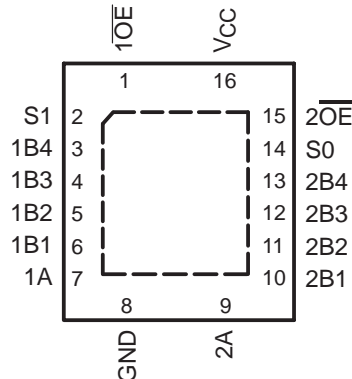
SCDS0180 – MAY 1995 – REVISED JANUARY 2004

## TTL-Compatible Input Levels

D, DB, DBQ, OR PW PACKAGE  
(TOP VIEW)



RGY PACKAGE  
(TOP VIEW)



## description/ordering information

The SN74CBT3253 is a dual 1-of-4 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

$\overline{1OE}$ ,  $\overline{2OE}$ , S0, and S1 select the appropriate B output for the A-input data.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Tape and reel	SN74CBT3253RGYR	CU253
	SOIC – D	Tube	SN74CBT3253D	CBT3253
		Tape and reel	SN74CBT3253DR	
	SSOP – DB	Tape and reel	SN74CBT3253DBR	CU253
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBT3253DBQR	CU253
	TSSOP – PW	Tube	SN74CBT3253PW	CU253
Tape and reel		SN74CBT3253PWR		

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE

INPUTS				FUNCTION
$\overline{1OE}$	$\overline{2OE}$	S1	S0	
X	H	X	X	Disconnect 1A and 2A
H	X	X	X	Disconnect 1A and 2A
L	L	L	L	1A to 1B1 and 2A to 2B1
L	L	L	H	1A to 1B2 and 2A to 2B2
L	L	H	L	1A to 1B3 and 2A to 2B3
L	L	H	H	1A to 1B4 and 2A to 2B4



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 **TEXAS  
INSTRUMENTS**

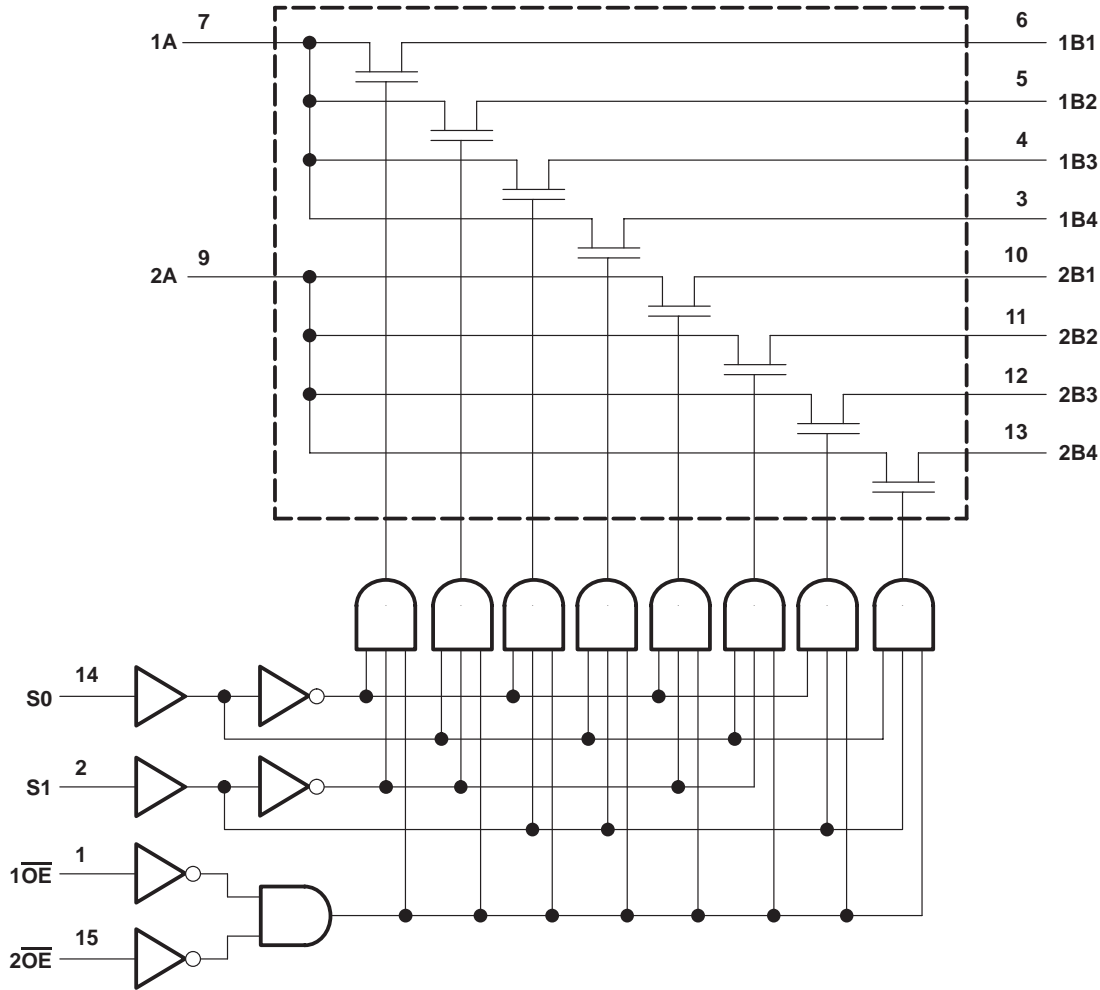
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# SN74CBT3253 DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

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## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to 7 V
Continuous channel current .....	128 mA
Input clamp current, $I_K$ ( $V_{I/O} < 0$ ) .....	-50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package .....	73°C/W
(see Note 2): DB package .....	82°C/W
(see Note 2): DBQ package .....	90°C/W
(see Note 2): PW package .....	108°C/W
(see Note 3): RGY package .....	39°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

3. The package thermal impedance is calculated in accordance with JESD 51-5.



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## DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

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### recommended operating conditions (see Note 4)

	MIN	MAX	UNIT
V <sub>CC</sub> Supply voltage	4	5.5	V
V <sub>IH</sub> High-level control input voltage	2		V
V <sub>IL</sub> Low-level control input voltage		0.8	V
T <sub>A</sub> Operating free-air temperature	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V <sub>IK</sub>		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2	V	
I <sub>I</sub>		V <sub>CC</sub> = 5 V,	V <sub>I</sub> = 5.5 V or GND			±1	μA	
I <sub>CC</sub>		V <sub>CC</sub> = 5.5 V,	I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND			3	μA	
ΔI <sub>CC</sub> ‡	Control inputs	V <sub>CC</sub> = 5.5 V,	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND			2.5	mA	
C <sub>i</sub>	Control inputs	V <sub>I</sub> = 3 V or 0				3.5	pF	
C <sub>io</sub> (OFF)	A port	V <sub>O</sub> = 3 V or 0, $\overline{OE} = V_{CC}$				10	pF	
	B port					4		
r <sub>on</sub> §		V <sub>CC</sub> = 4.5 V	V <sub>I</sub> = 0	I <sub>I</sub> = 64 mA		5	7	Ω
				I <sub>I</sub> = 30 mA		5	7	
			V <sub>I</sub> = 2.4 V,	I <sub>I</sub> = 15 mA		10	15	

† All typical values are at V<sub>CC</sub> = 5 V (unless otherwise noted), T<sub>A</sub> = 25°C.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V<sub>CC</sub> or GND.

§ Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower voltage of the two (A or B) terminals.

### switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4 V		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t <sub>pd</sub> ¶	A or B	B or A	0.35		0.25		ns
t <sub>pd</sub>	S	A or B	6.6		1.6	6.2	ns
t <sub>en</sub>	S	A or B	7.1		1.3	6.3	ns
	$\overline{OE}$		7.3		1.4	6.4	
t <sub>dis</sub>	S	A or B	7.9		1.1	7.4	ns
	$\overline{OE}$		7.3		2.3	7	

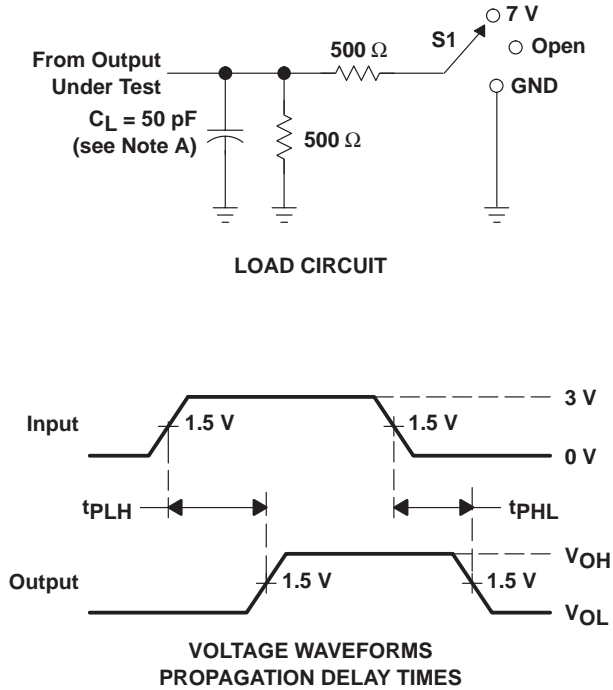
¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



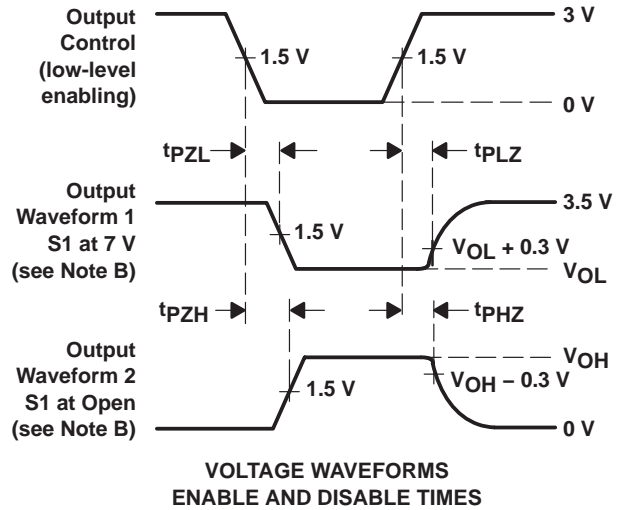
# SN74CBT3253 DUAL 1-OF-4 FET MULTIPLEXER/DEMULTIPLEXER

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## PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>pd</sub>	Open
t <sub>PZL</sub> /t <sub>PZL</sub>	7 V
t <sub>PHZ</sub> /t <sub>PZH</sub>	Open

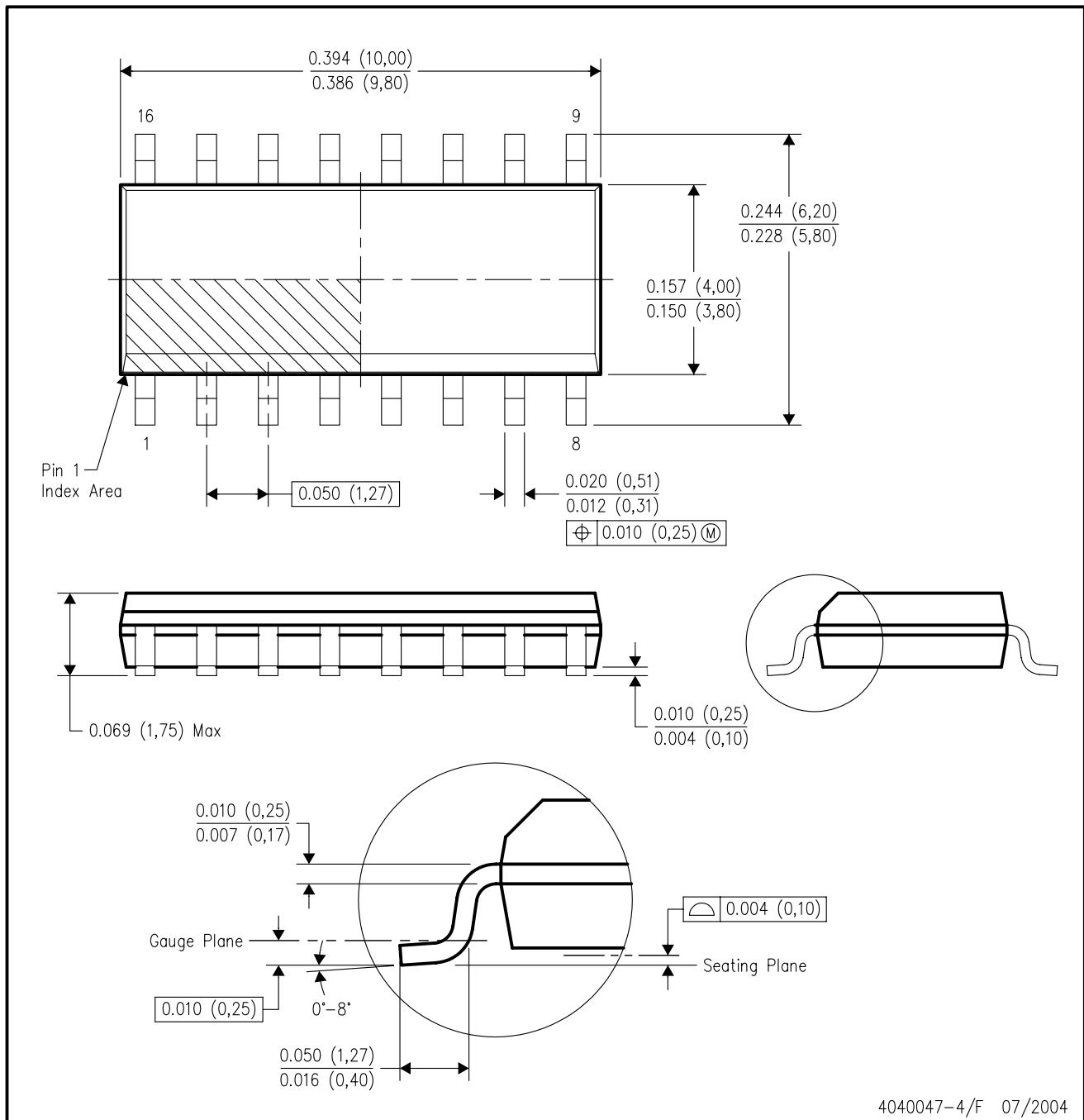


- NOTES:
- A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> ≤ 2.5 ns, t<sub>f</sub> ≤ 2.5 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. t<sub>PZL</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G. t<sub>PHL</sub> and t<sub>PLH</sub> are the same as t<sub>pd</sub>.
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

D (R-PDSO-G16)

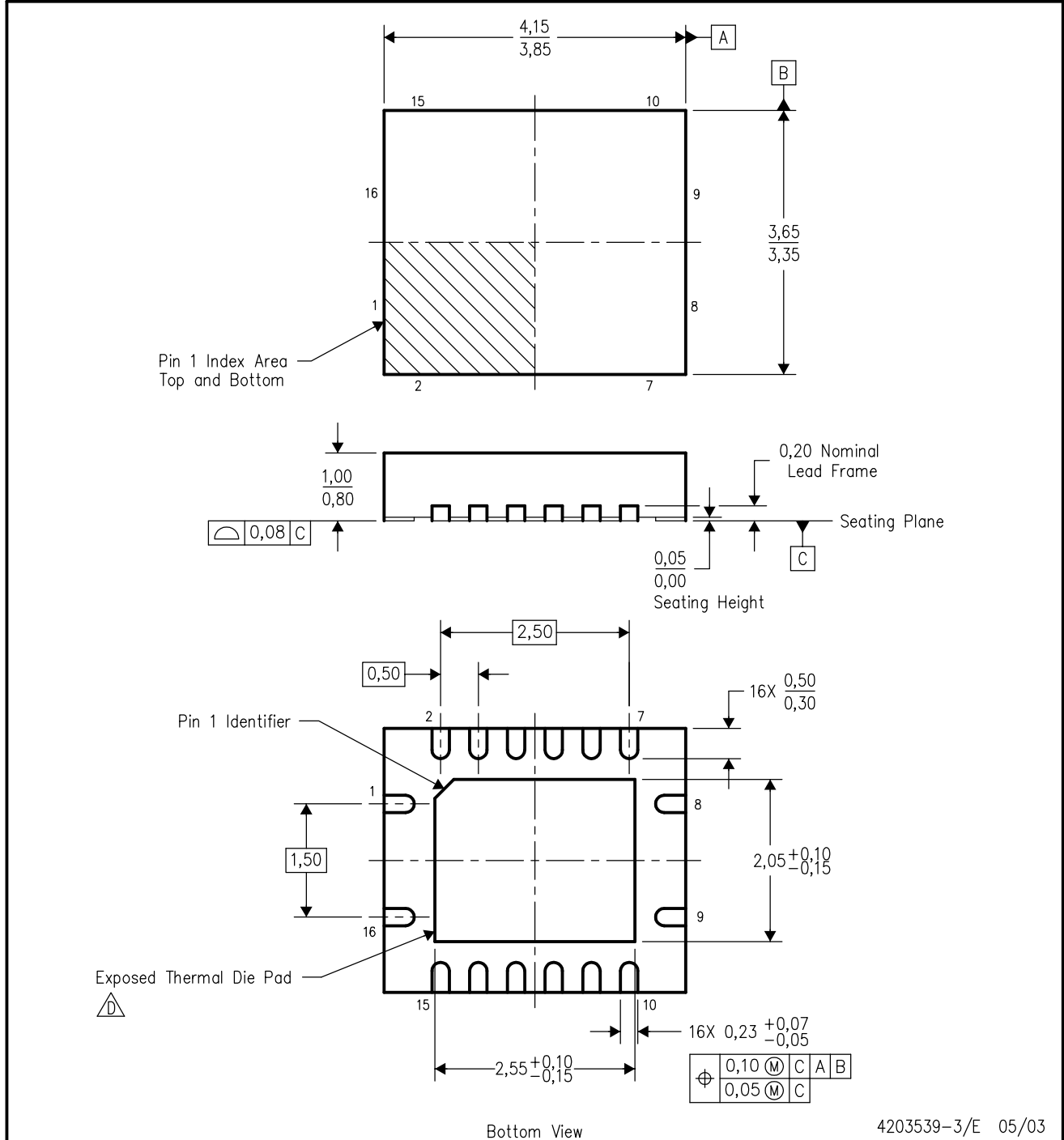
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-012 variation AC.


RGY (R-PQFP-N16)

PLASTIC QUAD FLATPACK



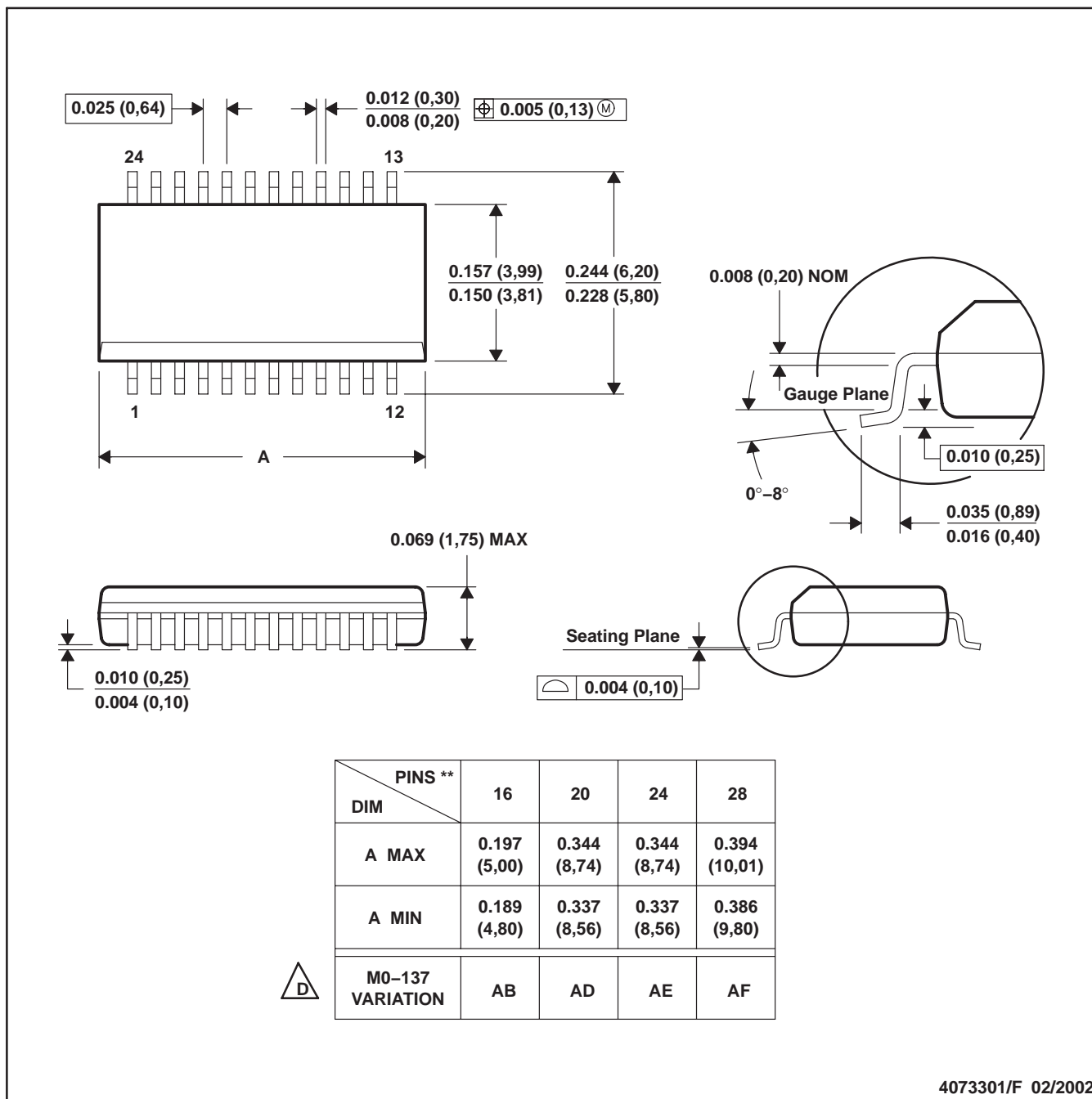
Bottom View

4203539-3/E 05/03

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  -  The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
  - E. Package complies to JEDEC MO-241 variation BB.

DBQ (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE



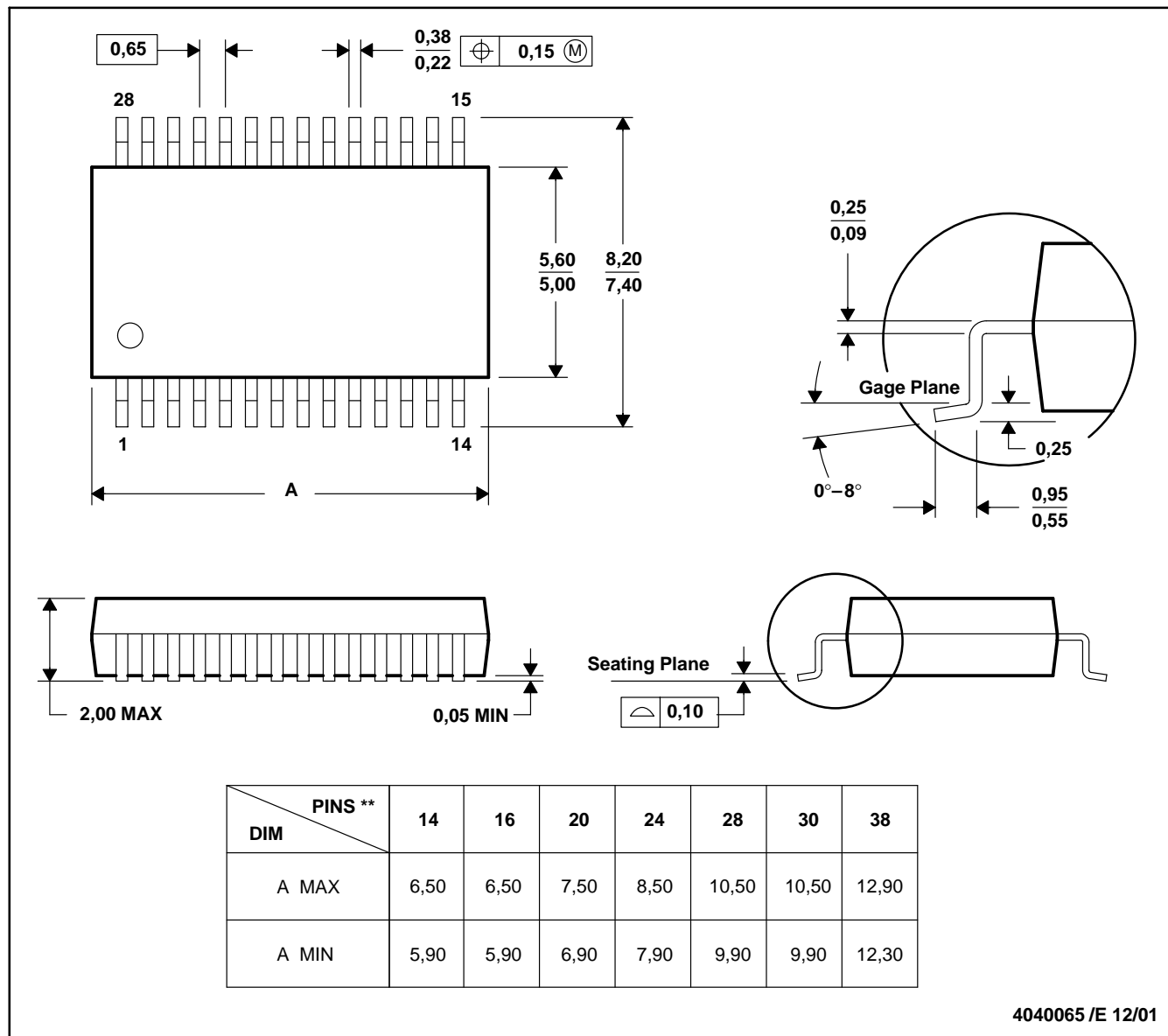
4073301/F 02/2002

- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MO-137.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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